

Title (en)

A METHOD FOR FABRICATING A FLEXIBLE ORGANIC LIGHT EMITTING DIODE USING A PRESSURE SENSITIVE ADHESIVE COMPOSITION

Title (de)

VERFAHREN ZUR HERSTELLUNG EINER FLEXIBLEN ORGANISCHEN LICHEMITTIERENDEN DIODE MITTELS EINER DRUCKEMPFLINDLICHEN KLEBSTOFFZUSAMMENSETZUNG

Title (fr)

MÉTHODE DE FABRICATION D'UNE DIODE ÉLECTROLUMINESCENTE ORGANIQUE FLEXIBLE À UTILISER UNE COMPOSITION ADHÉSIVE SENSIBLE À LA PRESSION

Publication

**EP 3645651 B1 20230906 (EN)**

Application

**EP 18797382 A 20181017**

Priority

- US 201762574344 P 20171019
- US 2018056175 W 20181017

Abstract (en)

[origin: WO2019079366A1] A pressure sensitive adhesive composition can cure via hydrosilylation to form a pressure sensitive adhesive. The pressure sensitive adhesive composition may be coated on a substrate and cured to form a protective film. The protective film is useful in flexible OLED device fabrication processes, e.g., for protection of passivation layers.

IPC 8 full level

**C09J 183/04** (2006.01); **C09J 7/38** (2018.01)

CPC (source: EP KR US)

**B32B 7/12** (2013.01 - US); **B32B 37/12** (2013.01 - US); **C09J 7/38** (2017.12 - EP KR US); **C09J 183/04** (2013.01 - EP KR US); **B32B 2457/206** (2013.01 - US); **C09J 2203/318** (2013.01 - EP KR US); **C09J 2483/00** (2013.01 - EP KR US); **Y02E 10/549** (2013.01 - EP)

Designated contracting state (EPC)

AL AT BE BG CH CY CZ DE DK EE ES FI FR GB GR HR HU IE IS IT LI LT LU LV MC MK MT NL NO PL PT RO RS SE SI SK SM TR

DOCDB simple family (publication)

**WO 2019079366 A1 20190425**; CN 111032814 A 20200417; CN 111032814 B 20220628; EP 3645651 A1 20200506; EP 3645651 B1 20230906; JP 2021500417 A 20210107; JP 7254065 B2 20230407; KR 102553390 B1 20230711; KR 20200087743 A 20200721; US 11549039 B2 20230110; US 2020392384 A1 20201217

DOCDB simple family (application)

**US 2018056175 W 20181017**; CN 201880050576 A 20181017; EP 18797382 A 20181017; JP 2020504715 A 20181017; KR 20207003025 A 20181017; US 201816635316 A 20181017